A new regime of nanoscale thermal transport: Collective diffusion increases dissipation efficiency

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In this contribution, we uncover a new regime of nanoscale thermal transport that dominates when the separation between nanoscale heat sources is small compared with the dominant phonon mean free paths. Surprisingly, the interaction of phonons originating from neighboring heat sources enables more efficient diffusive-like heat dissipation, even from nanoscale heat sources much smaller than the dominant phonon mean free paths. This finding suggests that thermal management in nanoscale systems including integrated circuits might not be as challenging as previously projected. Finally, we demonstrate a unique capability to extract differential conductivity as a function of phonon mean free path in materials, allowing the first (to our knowledge) experimental validation of predictions from the recently developed first-principles calculations.

Critical applications including thermoelectrics for energy harvesting, nanoparticle-mediated thermal therapies, nanoelectronic devices, and nanoelectronic and optoelectronic devices require a comprehensive understanding of energy flow at the nanoscale. Recent work has shown that the rate of heat dissipation from a heat source is reduced significantly below that predicted by Fourier’s law for diffusive heat transfer when the characteristic dimension of the heat source is smaller than the mean free path (MFP) of the dominant heat carriers (phonons in dielectric and semiconductor materials) (1–6). However, a complete fundamental description of nanoscale thermal transport is still elusive, and current theoretical efforts are limited by a lack of experimental validation.

Diffusive heat transfer requires many collisions among heat carriers to establish a local thermal equilibrium and a continuous temperature gradient along which energy dissipates. However, when the dimension of a heat source is smaller than the phonon MFP, the diffusion equation is intrinsically invalid because phonons move ballistically without collisions. The rate of nanoscale heat dissipation is significantly lower than the diffusive prediction such that smaller heat sources appear increasingly inefficient in dissipating heat. Furthermore, heat-carrying phonons in real materials have a wide distribution of MFPs, from several nanometers to hundreds of microns (7). For a given nanoscale heat source size, phonons with MFPs shorter than the hot-spot dimension remain fully diffusive and contribute to efficient heat dissipation and a high thermal conductivity (or equivalently, a low thermal resistivity). In contrast, phonons with long MFPs travel ballistically far from the heat source before scattering, with an effective thermal resistivity far larger than the diffusive prediction. Phonons with intermediate MFPs fall in between; here, heat transfer is quasiballistic with varying degrees of reduced contributions to the conduction of heat away from the nanoscale source.

Most work to date has explored the reduction in heat transfer from functionally isolated microscale and nanoscale heat sources (1–5). Indeed, characterizing heat transfer from micro/nanostructures with varying size can be used to experimentally measure cumulative phonon MFP spectra of materials (2, 8, 9), with the proof-of-principle demonstrated for long-MFP (>1-μm) phonons in silicon (3).

In this work, we show through both experiment and theory that the size of the heat source is not the only important scale that determines nanoscale heat dissipation. We identify a new regime of thermal transport that occurs when the separation between nanoscale heat sources is smaller than the average phonon MFP. Surprisingly, we find that when phonons from neighboring heat sources interact, more of them dissipate heat in a diffusive manner.

Significance

A complete description of nanoscale thermal transport is a fundamental problem that has defied understanding for many decades. Here, we uncover a surprising new regime of nanoscale thermal transport where, counterintuitively, nanoscale heat sources cool more quickly when placed close together than when they are widely separated. This increased cooling efficiency is possible when the separation between nanoscale heat sources is comparable to the average mean free paths of the dominant heat-carrying phonons. This finding suggests new approaches for addressing the significant challenge of thermal management in nanosystems, with design implications for integrated circuits, thermoelectric devices, nanoparticle-mediated thermal therapies, and nanoelectronic and optoelectronic devices for improving clean-energy technologies.


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regime, thus counteracting the inefficiency caused by ballistic effects in the case of isolated heat sources. This collective behavior can increase heat transfer to near the diffusive limit. Most importantly, the appearance of this “collectively diffusive” regime mitigates the scaling problems for thermal management in nanoelectronics, which may not be as serious as projected (2, 10, 11). Finally, we use this previously unobserved phenomenon to extract the contribution to thermal transport from specific regions of the phonon MFP spectrum, opening up a new approach for thermal transport metrology and MFP spectroscopy.

This is because by varying both nanostructure size and separation, an effective phonon filter is introduced that suppresses specific sections of MFP contributions to thermal conductivity. We compare our extracted phonon MFP spectra with predictions from first-principles calculations and find excellent agreement between experiment and theory. Looking forward, we have a unique capability for characterizing phonon transport in novel materials where predictions do not yet exist.

Fig. 1 illustrates the differences between the three regimes of heat transport from nanoscale heat sources—purely diffusive, quasi-ballistic, and collectively diffusive. Quasi-ballistic transport (Fig. 1B) dominates when the size of isolated nanoscale heat sources is smaller than dominant phonon MFPs. In the new collectively diffusive regime we uncovered (Fig. 1C), the separation between heat sources is small enough that long-MFP phonons, whose contribution to heat dissipation would normally be limited by the small size of nano-heat sources, can once again play a significant role and restore heat transfer efficiency to near the diffusive limit. Although these phonons travel ballistically away from each individual heat source, they can scatter with phonons originating from a neighboring heat source, thus creating an effectively larger heat source size. In the limiting case, the spacing between heat sources vanishes and this regime approaches heat dissipation from a uniformly heated layer.

Experiment

In our experiment, arrays of nickel nanowires were fabricated by e-beam lithography and lift-off techniques to form periodic gratings on the surface of sapphire and silicon substrates. The nanowire line widths \( L \) range from 750 nm down to 30 nm, with period \( P = 4L \) and a rectangular profile height of \( \sim 13.5 \) nm. The use of nanometered structures rather than optical absorption allows us to explore the dynamics of heat sources much smaller than the diffraction limit of visible light. The metallic nanowires are heated by a 25-fs pump pulse centered at a wavelength of 800 nm. The sapphire substrate is transparent at this wavelength, whereas the silicon substrate has such a long absorption depth that any small, uniform heating of the substrate can be neglected. Laser excitation thus creates an array of nanoscale hot spots (lines) on the surface of a cold substrate. Because all nanostructures are fabricated on the same substrate at the same time, the intrinsic thermal boundary resistivity at the interface between the metallic line and the substrate will be constant across all samples: any variation in efficiency of heat dissipation as the hot-spot size or spacing is varied can thus be attributed to different regimes of thermal transport.

The laser-induced thermal expansion and subsequent cooling of the nanogratings is probed using coherent extreme UV (EUV) light centered at a wavelength of 29 nm, created by high harmonic up-conversion of an 800-nm Ti:sapphire laser (12). The time delay between the EUV probe pulse and the laser pump pulse is adjusted using a mechanical delay stage between \( \sim 400 \) and \( +8,000 \) ps, with step size as small as 1 ps. As the EUV light diffracts from the periodic array of Ni nanowires, expansion and cooling of the nanogratings changes the diffraction efficiency, and this signal is recorded by a CCD camera as a function of delay time between pump and probe pulses. Examples of this dynamic signal are shown in Fig. 24. [Note that more details of the experimental setup are described elsewhere (13, 14) and in SI Text, section S1.] Because the reflectivities of these materials do not change with temperature at EUV wavelengths (15), the change in the diffraction signal can be uniquely attributed to physical deformations in the surface profile. Moreover, because the thermally expanded nanowires will change the diffraction signal as long as their temperature is higher than their initial state, this serves as a measure of the cooling rate of the nanowires rather than the rate of heat transfer across a specific distance as in optical transient grating (6) or buried-layer heating experiments (16). Thus, the data of Fig. 24 can be used to directly extract the average thermal expansion and relaxation of each individual nanowire induced by laser heating and subsequent heat dissipation into the substrate, in addition to the surface deformations caused by acoustic waves launched by the initial impulsive expansion (13, 14, 17).

Theory

To understand the different regimes of thermal transport illustrated in Fig. 1, we consider three models: (i) the model described in our previous work that assumes isolated heat sources (1); (ii) an analytical model we develop here to account for interactions of phonons originating from neighboring heat sources using a gray, single-phonon–MFP approximation; and (iii) a more advanced interacting model that includes a distribution of phonon MFPs. As discussed in detail below, this interacting multi-MFP model allows us to extract MFP-dependent contributions to thermal conductivity for MFPs as short as 14 nm for the first time (to our knowledge), providing data that can be directly compared with predictions from first-principles density functional theory (DFT).

To quantify the deviations from diffusive heat transport, we first build upon methods similar to those described by Siemens.
et al. (1), but including more comprehensive finite-element physical modeling (18) to improve data reduction accuracy. We model our system using diffusive heat conduction theory, while allowing the effective thermal boundary resistivity (which sets the temperature discontinuity across the boundary between the nickel nanowires and the substrate) to vary as a function of line width to account for nondiffusive effects in the substrate near the heat source.

We use accurate sample dimensions (height, line width, and period) characterized by atomic force microscopy (SI Text, section S1). Fresnel optical propagation is then used to calculate the diffraction signal from the simulated surface deformations. The effective boundary resistivity, \( r_{\text{eff}} \), that provides the best fit to the experimental data of Fig. 2A represents the sum of two terms: first, the constant intrinsic thermal boundary resistivity, \( r_{\text{TBR},i} \), that originates from the material difference between nickel and substrate; and second, a correction term, \( r_{\text{Corr}} \), due to nondiffusive transport in the substrate close to the heat source when either \( L \) or \( P \) is smaller than MFPs. Although this is a similar effective correction for nondiffusive transport near isolated nanoscale heat sources as that used in previous works (2–6), by assigning the nondiffusive contribution to the thermal boundary resistivity rather than to changes in the thermal conductivity of the substrate, we maintain a simple modeling geometry and avoid the need to assume a particular region of the substrate in which an effective conductivity change should apply. Further discussion can be found in SI Text, section S2.

The effective resistivity results are plotted in Fig. 2B. For large line widths on both sapphire and silicon substrates, the effective resistivity converges toward a constant value—the intrinsic thermal boundary resistivity. As the line width approaches the dominant phonon MFPs in the substrate, the effective resistivity rises as thermal transport becomes quasiballistic and the contribution to heat dissipation of long-MFP phonon modes is suppressed (1, 3, 8). This behavior was successfully described in past work using a simple gray model for sapphire and fused silica, which assumes a single-phonon MFP to loosely describe a weighted average of the MFPs from all of the phonon modes contributing to thermal transport in a given material. According to this model, a ballistic correction term proportional to \( \lambda_{\text{phon}} / L \) can be added to the intrinsic thermal boundary resistivity (1, 19); this prediction is plotted in dotted red in Fig. 2B. However, as the line width (and period) shrinks further, Fig. 2B shows that the effective resistivity starts to decrease rather than continuing to increase. The constant grating duty cycle for our series of samples means that the smallest-line width nanowires are also those with the smallest separation between neighboring heat sources. Thus, for small line widths, the separation becomes comparable to dominant phonon MFPs. For silicon, this peak in \( r_{\text{eff}} \) is shifted toward longer line widths/periods compared with sapphire because the phonon MFP distribution in silicon is also shifted toward longer MFPs, i.e., silicon has a longer average MFP than sapphire (1, 6). As illustrated in Fig. 1C, in this collectively diffusive regime, longer-MFP phonons from neighboring heat sources interact with each other as they would if they originated from a single, large heat source, leading to diffusive-like heat dissipation and decreasing the effective resistivity. The quasiballistic model for isolated heat sources clearly fails to capture this experimental observation, and a new model for \( r_{\text{Corr}} \) is required to account for the transition to this previously unpredicted and unobserved collectively diffusive regime.

We propose to use the concept of a notch filter in the MFP spectrum to describe the effects of grating line width and separation, shown schematically in Fig. 3A. The notch filter suppresses the contribution of phonon modes with MFPs that fall between the line width \( L \) and period \( P \) of the nanogratings. Thus, if the grating period (separation) remains large while the line width is decreased, one would expect the effective boundary resistivity to continue to rise, as shown in the red dotted lines of Fig. 2B. This is because the contributions of all phonon modes...
with MFPs longer than the line width \( L \) are suppressed in the quasiballistic regime of isolated heat sources. On the other hand, if the grating period shrinks, long-MFP phonon modes start to contribute again because phonons originating from neighboring heat sources interact with each other as they would in a bulk system, so the effective boundary resistivity should recover toward the bulk value, as seen experimentally in Fig. 2B. If this picture is true, then a nanograting with a small line width and large period (i.e., wide filter) should exhibit a slower thermal decay than the same line width grating with shorter period (i.e., narrower filter). Using a set of periodic nickel nanowires on silicon with varied duty cycle, we directly observed this pronounced difference as shown in Fig. 3B.

To build an analytical expression for \( r_{\text{Corr}} \) based on this idea, we use the concept of a phonon conductivity suppression function, \( S(L, P, \Lambda) \), similar to those described by others (8, 20). This suppression function is applied to a bulk differential conductivity spectrum versus phonon MFP of the substrate, \( k(\Lambda_i) \), to calculate an effective nanoscale conductivity \( K_{\text{nano}} \):

\[
K_{\text{nano}} = \sum k(\Lambda_i) \cdot S(L, P, \Lambda_i). \tag{1}
\]

We then relate \( r_{\text{Corr}} \) to the change in conductivity represented by this suppression:

\[
r_{\text{Corr}} = A \left( \frac{1}{K_{\text{nano}}} - \frac{1}{K_{\text{bulk}}} \right), \tag{2}
\]

where \( A \) collects geometrical constants (discussed further in SI Text, section S3) and \( K_{\text{bulk}} \) is the bulk conductivity of the substrate, simply given by \( \sum k(\Lambda_i) \). For a given phonon MFP \( \Lambda_i \), \( S \) must approach unity in the diffusive regime when both \( L \) and \( P \) are large and at the limit of uniform heating when \( L = P \). For the limit of small, isolated heat sources when \( L \to 0 \) but \( P \) is large, \( S \to L / (2 \Lambda) \) to reproduce the behavior of the previously published

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**Fig. 3.** Line width and period define a suppression filter for phonon MFP spectra. (A) The observed increase in effective thermal boundary resistivity for small line widths \( L \) is due to the suppression of the contribution to thermal conductivity of phonon modes with MFP larger than \( L \). Decreasing the period \( P \) can reactivate modes with MFP larger than \( P \), decreasing the effective resistivity. In the limiting case of a uniformly heated layer, \( P \) approaches \( L \) and all phonon modes participate in thermal transport. We use as an example the smoothed differential conductivity distribution for silicon (top graphs, green line), calculated from first-principles DFT (SI Text, section S4). (B) A comparison of the thermal decay of small line width gratings for two different periods directly validates the prediction of the suppression filter model, i.e., small line widths spaced far apart (red lines) exhibit a slower initial thermal decay than small line widths spaced closer together (blue lines). The dashed lines provide a guide to the eye for the thermal decay through the center of the acoustic oscillations.
quasi-ballistic model (1, 21). Finally, the effects of $L$ and $P$ should be the same but opposite to each other so that $L$ suppresses phonon mode contributions in the same way as $P$ reactivates them. To capture these behaviors along with smooth transitions among regimes, the two effects are represented by a special case of the generic family of logistic functions, where the total suppression function is written as follows:

$$S = \tanh\left(\frac{L}{\Delta L}\right) + \left[1 - \tanh\left(\frac{P}{\Delta P}\right)\right].$$  \hspace{1cm} \text{[3]}

More details of this suppression function can be found in SI Text, section S3. Although more rigorous methods of deriving suppression functions for various experimental geometries are currently being explored (9, 20, 22), none has yet sought to account for closely spaced heat sources or an accompanying reintroduction of phonon modes. Eq. 3 represents the first attempt (to our knowledge) to include the contribution of heat source spacing and offers a model that is simple enough for fast integration into existing models of heat transfer in nanoscale devices, for example, but complex enough to capture the previously unobserved behavior and make successful predictions.

To test this new model for $r_{\text{corr}}$, we first assume the simple single-MFP (gray) model (where the MFP distribution is a delta function). The resulting predictions are shown in the blue curves in Fig. 2B. Specifically, $r_{\text{corr}}$ in this case is given by the following:

$$r_{\text{corr, gray}}(L, P) = \frac{A}{K_{\text{bulk}}} \left(\frac{1}{S(L, P, L_{\text{gray}})} - 1\right).$$  \hspace{1cm} \text{[4]}

Fitting this interacting model to the $r_{\text{eff}}$ data for sapphire, we extract values for $T_{\text{BBR}}$ and $L_{\text{gray}}$ that are consistent with previous results (1): $L_{\text{gray, av}} = 131 \pm 11$ nm, $T_{\text{BBR, av}} = 2.58 \pm 0.19 \times 10^{-9}$ m$^2$K/W. This good agreement with the previous larger-line width data and the accurate fit for the full range of our data validate our interacting $r_{\text{corr}}$ model as an improved method to account for nanoscale size effects in heat transport—for both quasi-ballistic and collectively diffusive regimes. Interestingly, this single-MFP model provides a reasonable approximation for the entire range of heat transport in sapphire.

For silicon, the interacting $r_{\text{corr}}$ follows the general shape of the data and yields $L_{\text{gray, av}} = 306 \pm 17$ nm, which is consistent with previously reported values (6). However, the interacting gray-model approach, although more successful than the isolated model, fails to capture the additional structured tail in effective resistivity that appears for very small line widths and periods, below $L = 100$ nm. The failure of this approach is not surprising, because the single-MFP model is known to be a poor approximation for silicon with its broad distribution of phonon MFPs (8, 20).

**Discussion of Collectively Diffusive Regime and Extension to Phonon Mode Conductivity Spectra**

Having developed and validated the new model to capture the transitions from diffusive, to quasi-ballistic, to collectively diffusive regimes, we can now extend our calculations beyond the simple single-MFP model and use our data to extract the MFP-dependent contributions to thermal conductivity in different materials down to MFPs as small as 14 nm for the first time (to our knowledge). Because line width and period set the location and width of the effective notch filter in the phonon MFP spectrum, each configuration uniquely samples the contribution to thermal conductivity of different MFP ranges of phonon modes with a resolution controlled primarily by the number of configurations tested. The larger the resistivity correction needed for a given nanograting, the stronger the conductivity contribution of phonon modes that were suppressed.

To extract information about the differential conductivity spectrum, we use the full multi-MFP form of $r_{\text{corr}}$, given by the following:

$$r_{\text{corr}}(L, P) = \frac{1}{A} \left(\sum_{i} k(L_i) S(L, P, L_i) - 1\right) / K_{\text{bulk}}.$$  \hspace{1cm} \text{[5]}

We partition the full sum in bins according to the MFP sensitivity of each grating configuration (SI Text, section S3). Then by fitting our set of $r_{\text{eff}}$ data as $r_{\text{eff}} = r_{\text{BBR}} + r_{\text{corr}}$, we extract the average $k(L_i)$ that is associated with all modes $L_i$ within each bin, thus assessing the relative contributions to thermal conductivity of each region of the phonon MFP spectrum (plotted in Fig. 4). By limiting the number of bins to be no more than one-half of our number of data points, we ensure a conservative, well-conditioned fit, although we note that changing the bin number does not substantially alter the trends we observe. As shown by the purple curves in Fig. 2B, for sapphire, this procedure matches the experimentally measured $r_{\text{eff}}$ as well as the gray model for interacting heat sources. For silicon, this more complete multiple-MFP interacting model is able to match our experimental measurements of thermal boundary resistivity over diffusive, quasi-ballistic and collectively diffusive regimes, including the exceptionally slow drop in resistivity for small line widths below 100 nm.

Although the number of experimental data points limits the number of regions we can reasonably consider in this first demonstration, this approach still offers unprecedented experimental access to the differential thermal conductivity contributions of phonons with different MFPs and for benchmarking theoretical predictions, including those from first-principles DFT calculations shown in Figs. 3 and 4. In particular, our experimental data across all MFP ranges measured in silicon are in very good agreement with our DFT calculations [which also agree with those in the literature (8)]. However, some small discrepancies appear for
phonon MFPs around ~100 nm, where experimental verification was not possible before. Differences between the experimental and theoretical spectra in this region may also be exaggerated by our limited set of small-line width gratings; increased resolution with a larger sample set can address this issue. Our data are also consistent with observations by others that emphasize significant contributions from long-MFP (>1-μm) modes (2, 3, 6), but the limited number of data points we have for structures much larger than the average phonon MFP results in a relatively large uncertainty in this region. For the purpose of comparison in Fig. 4, we normalized the experimental spectra in silicon by assuming the integrated conductivity up to 1 μm should match that calculated by DFT.

For silicon, both calculation and experimental data imply that phonons with MFPs shorter than 1 μm are responsible for >95% of the thermal conductivity. The discrepancy below 300 nm between experimental and theoretical curves (apparent in the cumulative distribution) is due to two factors. First, the sharper rise in the DFT cumulative curve arises due to the very strong short-MFP peak in the conductivity spectrum—a peak that lies at ~5 nm, below the lower bound of our experimental sensitivity (14 nm) using 30-nm structures. Thus, the experimental data simply do not include the shortest phonon MFP peak. Second, because of the complex crystal structure of sapphire, the DFT calculations required the use of relatively small interaction-distance cutoffs for determining the harmonic and anharmonic force constants, which may cause a larger error in the predictions than for silicon.

There are two significant advantages of our EUV-based technique compared with previously reported MFP spectroscopy techniques. First, our approach combines nanoheaters with the phase sensitivity of short-wavelength probes is the only way to experimentally access dimensions far below 100 nm to directly resolve the contributions of phonons with MFP down to 14 nm. Other approaches require numerical extrapolation techniques and interpretation, which are still being developed (9). Second, characterizing phonon MFP spectra by harnessing interacting nanoscale heat sources allows us to probe arbitrary segments of the MFP spectrum for any novel material, enabling direct access to the differential, rather than only the cumulative, MFP distribution.

The ability to experimentally extract a phonon MFP distribution down to such small MFPs offers an exceptional, useful method for validating existing first-principles predictions across the whole range of phonon MFPs significant for heat conduction, as well as the first access to such information for more complex materials where calculations have not yet been performed. Furthermore, combined knowledge of both the differential and cumulative spectra may offer intriguing insight into the full MFP spectrum with the detail necessary for accurate prediction of heat transfer in nanostructured systems.

Conclusion
In summary, we uncover a new regime of nanoscale thermal transport that dominates when the separation between nanoscale heat sources is small compared with the dominant phonon MFPs. We also present a new approach for characterizing the relative contributions of phonons with different MFPs that participate strongly in heat conduction. In particular, we can probe the small-MFP regime, which has been previously inaccessible to experiment. This unique capability is important as the need for precise phonon MFP distributions in complex nanostructures becomes more pressing—for both fundamental understanding and to harness systems where modeling does not yet exist. In the future, because bright soft X-ray high harmonic sources can now reach wavelengths below 1 nm (23), this approach can be extended even further into the deep nanoregime. In addition, more comprehensive and fundamental insight into nanoscale thermal transport may be possible by adopting the framework created to bridge all types of anomalous diffusion (24–27), which does not rely on effective diffusion models for inherently nondiffusive heat transfer. Finally, the efficient, collectively diffusive regime of thermal transport that we observe for the first time can potentially mitigate projected problems for thermal management in nanoelectronics, wherein the power density is likely to increase as the individual nanostructures shrink in size (10, 11). It also highlights important design implications for nanostructured materials and devices for energy and biomedical applications.

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Supporting Information

Hoogeboom-Pot et al. 10.1073/pnas.1503449112

SI Text

S1. Experimental Setup and Samples

For the time-resolved diffraction measurement, we used the pump–probe system described in our previous work (1, 2). The pump and probe pulses are derived from the same Ti:sapphire amplifier system (centered at a wavelength of 800 nm, with 4- to 6-kHz repetition rate, 1.5- to 2-mJ pulse energy, and 25-fs pulse length) as shown in Fig. S1. The probe beam is focused into an argon-filled hollow waveguide to generate short-wavelength (centered at 29 nm) extreme UV (EUV) light via the nonlinear process of high-order harmonic generation (3). The very short wavelength and interferometric diffraction measurement gives us high lateral and axial spatial resolution to follow the dynamics in nanostructured systems with sensitivity to surface displacements at the picometer scale. The EUV beam is focused onto the sample using a grazing-incidence toroidal mirror to a diameter of ~100 μm (smaller than the 120 × 120-μm patterned area).

To ensure uniform heating of the nanogratings, the pump beam is kept relatively large with a diameter of ~400–500 μm and a fluence of ≤10 mJ/cm². The height of the nickel nanostructures is chosen to be less than or equal to the absorption depth of the infrared pump light for nearly uniform heating in the vertical direction as well. By testing the thermal decay dynamics with multiple pump fluences, we ensure that all our measurements are taken within the linear regime of heat transfer.

Because nickel is a metal, most of the heat is carried by electrons inside the nanostructures. Strong electron–phonon coupling ensures that the lattice has thermalized with the electrons within the first 10 ps—much faster than the timescale of thermal decay we are investigating. Because electron mean free paths (MFPs) are much smaller than all of the structures we explore, no significant nanoscale thermal conductivity effects should be expected in the nickel nanostructures.

To accurately characterize the sample (in terms of line width, height, and period of the nanograting) and design the unit cell in the finite-element simulations of the heat transport and thermal expansion, we imaged each sample using atomic force microscopy and scanning electron microscopy. We observed good uniformity across the nanostructures, as shown in the representative images in Fig. S2 B and C.

S2. Finite-Element Multiphysics Modeling for Experimental Data Analysis

To quantitatively analyze the different regimes of nanoscale thermal transport illustrated in Fig. 1 of the main text, we use a similar approach as that described by Siemens et al. (4), but with a more comprehensive finite-element physical modeling approach (5) to reduce uncertainty in the comparison between experimental observations and the simulation output. We model our experimental observation using a 2D simulation unit cell with the plane strain approximation to follow the full thermal expansion and cooling dynamics of the nickel nanogratings on the sapphire and silicon substrates (6). The nanograting geometry allows for periodic boundary conditions for the temperature $T$ and the displacement $u$ on the sides of the unit cell. All mesh points are initialized at room temperature and zero displacement ($T = 293$ K, $u = 0$). The top boundaries are free to move but heat flux across them is set to zero (no radiative heat dissipation). Continuity in the displacement is enforced at the interface between the Ni structure and the substrate, effectively joining the two materials such that no slipping is allowed. The bottom boundary is fixed, and the heat flux across it is also set to zero. The height of the substrate section is set to 10 μm, much larger than the maximum thermal penetration depths of 0.85 μm in silicon and 0.35 μm in sapphire, to ensure no excess heat reaches the bottom boundary during the simulation time (up to 8 ns). An example of the top region of the unit cell geometry and mesh profile for the finite-element simulations is illustrated in Fig. S3.

Unlike Siemens et al. (4), we incorporate the inertial terms in the initial thermal expansion and solve the coupled equations for the profiles of $T$ and $u$ in the time domain (7):

$$\nabla \cdot (c : \nabla (u - a\Delta T)) = \rho \frac{\partial^2 u}{\partial t^2}, \quad [S1]$$

$$\rho C_p \frac{\partial T}{\partial t} + \rho C_p u \cdot \nabla T = \nabla \cdot (K_{\text{bulk}} \nabla T) + Q. \quad [S2]$$

where $c$ is the elastic tensor, $u$ is the displacement, $\rho$ is the density of the material, $a$ is the linear coefficient of thermal expansion, $T$ is the temperature, $C_p$ is the specific heat of the material, $K_{\text{bulk}}$ is the bulk thermal conductivity, and $Q$ is the heat source term accounting for the laser heating of the nanograting, as described by Banfi et al. (8). The more complete account of the physical dynamics in our sample allows for a more precise fit to our data and lowers our uncertainty, particular for small-line width samples.

The effective thermal boundary resistivity $r_{\text{eff}}$, which sets the temperature discontinuity, $\Delta T$, across the boundary between the nickel nanostructures and the substrate, is introduced with the following equation:

$$n \cdot (K_{\text{bulk}} \nabla T) = -\frac{\Delta T}{r_{\text{eff}}}. \quad [S3]$$

where $n$ is the unit vector normal to substrate surface.

The simulations provide a time-dependent surface deformation profile, as illustrated in Fig. S3B. Fresnel optical propagation is used to calculate the dynamic diffraction signal from these deformations, which can be directly compared with our experimental observations. For each sample geometry, we calculate the diffraction signals from a comprehensive set of deformation profiles related to different values of $r_{\text{eff}}$. The effective resistivity $r_{\text{eff}}$ that then provides the best fit to the experimental data is selected to represent the sum of the constant intrinsic thermal boundary resistivity, $r_{\text{BBR}}$, and corrections due to the nanoscale size effects, $r_{\text{corr}}$. Insight into the expected size dependence of this correction can be gained from simple models for isolated heat sources from Wexler (9) and Prasher (10). They approximate thermal resistance due to a constriction, $R_c$, as a sum of a diffusive and ballistic term. In the cylindrical geometry discussed by Siemens et al. (4), these terms are given by the following:

$$R_c = \ln \left( \frac{P_{\text{in}}}{K_{\text{bulk}} \pi M} \right) + \frac{4\Lambda_{\text{ray}}}{K_{\text{bulk}} \pi (L/2) M} \quad [S4]$$

where $M$ is the length of the nanowire. To fit our data to a purely diffusive model, we effectively set this sum of terms equal to a single diffusive term with a modified thermal conductivity, $K_{\text{nano}}$, similar to the practice in existing literature.
The size of the region where ballistic effects are important should be determined only by the phonon MFP distribution, so although the size of the region where ballistic effects are important should be determined only by the phonon MFP distribution, so although $d$ can depend on $\Lambda_{\text{ray}}$ of the substrate, it should have no dependence on $L$ or $P$.

This type of correction was also discussed by Chen (11) and has been widely used in past works (4, 12–16) to account for non-diffusive thermal transport near isolated nanoscale heat sources. The unique insights we present here address how heat transfer is also changed due to the interactions between neighboring nanoscale heat sources and how it is determined by both phonon MFP spectra and heat source arrangements.

All of the material properties used in the finite-element multiphysics modeling are listed in Table S1. Given the maximum substrate temperature change induced in our experiment of $\pm 40$ K, the specific heat and bulk thermal conductivity can change by $\pm 10\%$, and we confirm that any change of this magnitude does not cause appreciable differences in the simulated time-dependent diffraction signal we use to compare with experimental data. Moreover, because we observe no pump-fluence dependence in the normalized signals, precise choices for simulation temperatures will not affect the resulting comparison with experimental data.

### S3. Model for Interacting Heat Sources

In this work, we introduce a new model to account for the size effects observed in our measurement by using a suppression filter in the phonon MFP spectrum of differential thermal conductivity. The model is derived from the physical limits of diffusive heat transport both for large-line width structures and for the case of uniform heating when period equals line width, as well as the analytically derived resistivity correction for small isolated line heat sources shown above and a particular MFP, $\Lambda$:

$$r_{\text{Corr, iso}} \propto \frac{\Lambda}{(L/2)}.$$  \[(S7)\]

In addition, we assume that the filter function should be smooth and that the effects of $L$ and $P$ are uncoupled and the same but opposite to each other. The relevant nondimensional variables are $L/\Lambda$ and $P/\Lambda$. All of this behavior is captured by a special case of the generic family of logistic functions:

$$S_L(L/\Lambda) = \tanh\left(\frac{L}{2\Lambda}\right),$$  \[(S8)\]

$$S_P(P/\Lambda) = 1 - \tanh\left(\frac{P}{2\Lambda}\right),$$  \[(S9)\]

$$S_{\text{total}}(L,P,\Lambda) = S_L + S_P.$$  \[(S10)\]

These functions are plotted in Fig. S4A, where we can see the similarity between the shape of $S_{\text{total}}$ and standard notch filters. This suppression function can then be applied to each individual MFP-dependent contribution to thermal conductivity to calculate an effective $K_{\text{eff}} = \sum k(\Lambda_i) \cdot S(L, P, \Lambda_i)$.

The resistivity correction for heat transport from interacting nanoscale heat sources can again be related to the change in conductivity imposed by the suppression function:

$$r_{\text{Corr, int}} \lesssim \frac{1}{K_{\text{nano}}} - \frac{1}{K_{\text{bulk}}}.$$  \[(S11)\]

which gives the following:

$$r_{\text{Corr, int}}(L, P) = A \left(\frac{1}{\sum k(\Lambda_i) S(L, P, \Lambda_i)} - \frac{1}{\sum k(\Lambda_i)}\right).$$  \[(S12)\]

The proportionality constant, $A$, incorporates geometrical constants along with the length scale introduced by the transformation from conductivity to resistivity. We associate this length scale with a finite region within radius $d$ near the heat source in which effective conductivity is modified from the bulk value, and the present model assumes that this length scale is the same for all phonon modes. The correspondence between this model and the previous isolated model (Eq. S4) shows that $A$ for the 1D line geometry could be written as follows:

$$A = d \ln(P/L).$$  \[(S13)\]

Under this assumption, fitting our data with the full multi-MFP interacting model yields values $d_{\text{app}} = 123 \pm 10$ nm and $d_S = 665 \pm 75$ nm. These correspond to one or two times the gray MFP value, which is the region in which one could intuitively expect most nondiffusive effects to be important. We do note that this form for the constant fails in the limit of $P \to \infty$ for the case of varying duty cycles, because it implies a divergent $r_{\text{Corr}}$ regardless of the comparison between $L$ and $\Lambda$. However, our data analysis simply fits $A$ as a single scaling constant (with the constant duty cycle describing our data), which does not affect any of the other parameters extracted through the fitting processes. Furthermore, all our simulations and fitting procedures for analyzing our data exist in the effective resistivity picture so that we never need to assume what the length scale, $d$, might be.

Using the gray model assuming a single MFP (as in the blue curves found in Fig. 2B), the derived $r_{\text{Corr, iso}}$ yields a reasonably good approximation for sapphire, but not for silicon. Both are well fit by including the extension to multiple MFPS.

Our model can be used in combination with calculated differential conductivity distributions (like the one shown in Fig. 3A) to test how well they can account for our observations of $r_{\text{Corr, iso}}$ including in particular the double-peak structure we observe for the silicon substrate. It can also be inverted to allow the extraction of differential conductivity information from $r_{\text{Corr, data}}$ as shown in Fig. 4.

The upper and lower bounds of the full range of MFP contributions to which we are sensitive are set by the suppression functions related to each of our nanogratings. We choose the minimum (14-nm) and maximum (5-µm) MFPS of our experimental spectrum to include only MFPS that are suppressed by at least 20% in our smallest and largest sample geometries, respectively. As can be seen in Fig. S4B, each particular configuration for $L$ and $P$ can be related to one most-suppressed MFP—at the minimum of $S_{\text{total}}$. We use this information from our set of nanogratings to set the MFP bins that we use when fitting $r_{\text{Corr, data}}$ in the full interacting multi-MFP model, as shown in Fig. S4B: bin boundaries are chosen halfway between neighboring most-suppressed MFPS.

The weights $k(\Lambda_i)$ fit to each bin give their relative contribution per nanometer to the differential thermal conductivity. The error bars in the histograms of Fig. 4 are obtained by varying $k(\Lambda_i)$ while maintaining the residual of the fit within the range of experimental uncertainty to explore the full range of weights allowed by the shape of the data.

Hoogeboom-Pot et al. www.pnas.org/cgi/content/short/1503449112
The analytical model described by Eq. S12 also reveals the connection between $r_{\text{eff}}$ and the effective thermal conductivity $K_{\text{nano}}$, for each line width–period pair. This can allow a more direct comparison with those experimental geometries without interfaces, which measure an effective conductivity. Specifically, the relative effective conductivity is given by the following:

$$
\frac{K_{\text{nano}}}{K_{\text{bulk}}} (L, P) = \frac{A}{K_{\text{bulk}}} r_{\text{eff}} (L, P) - r_{\text{BEB}} + A \frac{1}{K_{\text{bulk}}}^{-1}.
$$

It is important to note that different experimental geometries (for example, 1D- versus 2D-confined heat sources, or bulk materials compared with thin films compared with nanotubes) will result in observed conductivities that are specific to the given geometry. Consequently, effective thermal conductivity results cannot necessarily be compared in a straightforward manner. However, the phonon MFP spectrum corresponds to a physically real attribute of a material alone and therefore provides the more appropriate tool for comparison across different experimental geometries. Furthermore, the effective thermal conductivity for any experimental geometry can then be predicted using an experimental phonon MFP spectrum combined with the appropriate theoretical model for conductivity suppression. We note that, although both heat source geometry and spacing must be included in such suppression functions, spacing effects have only recently been explored, both by our group (17, 18) and more recently by numerical studies with a gray phonon model (19) using the phonon Boltzmann transport equation (20).

S4. Thermal Conductivity and Phonon MFP Spectra from First-Principles Calculations

First-principle-based methods for calculating the phononic thermal conductivity for a variety of bulk and nanostructured materials have recently been developed (21–23), where great agreement with the measured thermal conductivity values at different temperatures has been demonstrated. These calculations can differentiate the contributions to the total thermal conductivity of phonons with different wavelengths and different MFPs. Here, we follow the work by Esfarjani et al. (21) to calculate the thermal conductivities and phonon MFP distributions of silicon and sapphire under the relaxation time approximation.

In approach, the second-order harmonic and third-order anharmonic interatomic force constants are extracted from first-principles calculations using the direct method (24). We first record the net forces on all atoms in a supercell ($2 \times 2 \times 2$ conventional unit cells for silicon and $3 \times 3 \times 3$ primitive unit cells for sapphire) when one or two atoms are displaced from their equilibrium positions by steps of 0.015 Å up to a maximum displacement ($d_{\text{max}}$). A fit to the resulting force–displacement curves yields both the harmonic second-order and anharmonic third-order force constants (24). For the harmonic interaction, $d_{\text{max}}$ is set to 5.8 Å for silicon and 5.1 Å for sapphire, whereas the cutoffs for the third-order anharmonic interaction are 3.9 Å and 2.5 Å, respectively. The cutoffs are chosen by considering the balance between accuracy and computational power. In particular, the cutoffs for silicon are similar to the values used by Esfarjani et al. (21), which reproduced the experimental measurements of silicon phonon dispersion and thermal conductivity very well. Due to the complexity of the crystal structure of sapphire, we have to limit the interaction within a smaller range so that the number of force constants is reasonable to handle. Although we use a relatively small cutoff for sapphire, we impose translational invariance (24) to make sure that the force constants extracted are physically reasonable. All first-principles calculations are performed using the Vienna Ab initio Simulation Package (25) with the projector augmented wave pseudopotential (26) and the local-density approximation functional. The kinetic-energy cutoff for the plane-wave basis is set at 500 eV. The $4 \times 4 \times 4$ and $2 \times 2 \times 2$ k-meshes are used to sample the reciprocal space of silicon and sapphire, respectively. The choice of the energy cutoff and k-mesh ensures that the energy change is smaller than 1 meV/atom when refining these two parameters.

After extracting the harmonic force constants, the phonon dispersion relation can be calculated. Fig. S5 A and B shows the calculated phonon dispersion curves and phonon density of states (DOS) for silicon and sapphire. We also plot the phonon dispersion measured by neutron-scattering experiments (27, 28) as well as the DOS from other first-principles calculations (21, 29). The good agreement with both the measurements and other theoretical work validates the interatomic force constants from our first-principles calculations.

Using the anharmonic third-order force constants, the scattering rate of three-phonon processes can be calculated using Fermi’s golden rule (21, 30). The phonon lifetime $\tau_q$ of each mode $\mathbf{q}$ (the $s$th mode at wave vector $\mathbf{q}$) is computed by summing up the scattering rates of all possible three-phonon scattering events.

Defining the MFP $\Lambda_\mathbf{q}$ as $v_q \tau_q$, where $v_q$ is the group velocity of mode $\mathbf{q}$, the phonon thermal conductivity can be expressed as a function of $\Lambda_\mathbf{q}$:

$$
K = \frac{1}{3} \sum_q C_q v_q \Lambda_\mathbf{q}.
$$

where $C_q$ is the mode heat capacity. The calculated temperature-dependent thermal conductivity of silicon and sapphire is presented in Fig. S5 C and D, as well as predictions for silicon from other theoretical calculations based on similar approaches (21, 31) and experimental data for both silicon (32) and sapphire (33). Our calculations are in good agreement with these previous works.

The differential thermal conductivity $(dK/d\Lambda)\Delta\Lambda$ gives the contribution from the phonons with MFP between $\Lambda - \Delta\Lambda/2$ and $\Lambda + \Delta\Lambda/2$ to the total thermal conductivity. By summing up the thermal conductivity of phonon modes with MFPs in that range, the differential thermal conductivity can be determined. Fig. S6 shows the differential and cumulative thermal conductivity of silicon from first-principles calculations. Our calculated cumulative thermal conductivity for silicon is similar to the work by Esfarjani et al. (21). The differential thermal conductivity curve illustrated in Fig. S6 is discontinuous because only a finite number of sampling points are used in the first Brillouin zone. Because only the MFP of phonon modes at these points can be accurately evaluated, it is a common practice to assume each sampling point represents a neighboring region (21), as illustrated by the red box in Fig. S7, in which all phonon modes have the same MFP and mode thermal conductivity. As a result, the differential thermal conductivity in Fig. S6 displays discrete spikes in MFP. To obtain the continuous MFP spectrum, we linearly interpolate the MFP of the phonon modes between the sampling points along the direction of a reciprocal vector, while assuming the mode thermal conductivity is the average value of the neighboring phonon modes on the mesh. This interpolation procedure is illustrated in Fig. S7 and is found to preserve the total thermal conductivity and the shape of the cumulative thermal conductivity function, as shown in Fig. S8.

Fig. S1. Experimental setup. Schematic illustration of the pump-probe diffraction measurement, adapted from Siemens et al. (1).


Fig. S2. Sample geometry. (A) Schematic illustration of the pump and probe beam illumination geometry at the sample. Each sample is characterized with (B) scanning electron microscopy and (C) atomic force microscopy to have accurate dimensions (line width, height, and period of the nanograting) as inputs for the finite-element simulations of the heat transport and thermal expansion. Shown here is one particular nickel-on-sapphire sample with $L = 100$ nm (line width measured at the top of the nanowire).

Fig. S3. Top section of finite element simulation cell. (A) The simulation mesh concentrates points inside the nanostructure and near the interface. (B) The simulations output the time-dependent surface displacements following laser heating of the nanograting (the surface deformation is here amplified for the purpose of visualization).
Fig. S4. Visualizing phonon mode suppression. (A) For a phonon mode with a given MFP, $S_L$ describes the suppression of this mode’s contribution to thermal conductivity as the line width of a heat source decreases. $S_p$ undoes this suppression, and $S_{total}$ represents the total suppression when both small heat source and interaction between heat sources are taken into account. Thus, each configuration for $L$ and $P$ can be related to one most-suppressed MFP (minimum of $S_{total}$). (B) We use this information to set the MFP bins used when fitting $r_{eff}$ data in the full interacting multi-MFP model.
Comparing our DFT calculations with published work. Calculated phonon dispersion relation and DOS of silicon (A) and sapphire (B) are shown in blue. The red dots in A represent the measured silicon phonon dispersion by Nilsson and Nelin (1), whereas the orange curve is the DOS of silicon calculated by Esfarjani et al. (2). The red dots in B represent the measured sapphire phonon dispersion by Schober et al. (3), and the orange curve is the calculated DOS by Heid et al. (4). Calculated thermal conductivity curves for silicon (C) and sapphire (D) are shown in blue. The red dots in C represent the measured thermal conductivity of isotope-enriched silicon by Inyushkin et al. (5), whereas the orange and green curves are other previous theoretical calculations (2, 6). The red dots in D show the experimentally measured thermal conductivity for sapphire (7).

Fig. S6. Thermal conductivity MFP spectra. The differential (blue) and cumulative thermal conductivity (green) of silicon are reported. We also show the cumulative thermal conductivity calculated by Esfarjani et al. (1) (orange).


Fig. S7. Schematic of the interpolation process. The first-principles calculations assume that all phonon modes contained within the red box around mesh point \( q_i \) have the same MFP and thermal conductivity as the mode on the mesh point, resulting in discrete spikes in the differential conductivity spectrum. To build the continuous function implied by the discrete spectrum, we interpolate the MFP of phonons in the region represented by the blue box in between the neighboring mesh points and assign to them the average mode thermal conductivity as shown in the bottom two graphs.
Fig. S8. Interpolating the discrete spectrum. The smoothed differential (red) and cumulative thermal conductivity (purple) compare well with the discrete, raw spectra (blue and green, respectively).

Table S1. Material parameters used in multiphysics simulations

<table>
<thead>
<tr>
<th>Material properties</th>
<th>Nickel</th>
<th>Silicon</th>
<th>Sapphire</th>
</tr>
</thead>
<tbody>
<tr>
<td>$C_p$, specific heat (at 300 K), J/(kg·K)</td>
<td>456.8 (1)</td>
<td>710.0 (2)</td>
<td>657.5 (1)</td>
</tr>
<tr>
<td>$K_{\text{bulk}}$, bulk thermal conductivity, W/(m·K)</td>
<td>90.9 (2)</td>
<td>149.0 (3)</td>
<td>41.1 (1)</td>
</tr>
<tr>
<td>Debye temperature, K (4)</td>
<td>450</td>
<td>645</td>
<td>1047</td>
</tr>
<tr>
<td>Poisson’s ratio (5)</td>
<td>0.31</td>
<td>0.27</td>
<td>0.25</td>
</tr>
<tr>
<td>Young's modulus, $10^{11}$ Pa</td>
<td>2.00 (6)</td>
<td>1.31 (7)</td>
<td>3.45 (8)</td>
</tr>
<tr>
<td>$\alpha$, linear coefficient of thermal expansion, $10^{-6}$/K</td>
<td>12.77 (1)</td>
<td>3.00 (9)</td>
<td>5.21 (1)</td>
</tr>
<tr>
<td>$\rho$, density, kg/m$^3$</td>
<td>8,910 (1)</td>
<td>2,330 (10)</td>
<td>4,000 (1)</td>
</tr>
</tbody>
</table>